

Please Direct All Correspondence to Customer Number **20995****AMENDMENT / RESPONSE TRANSMITTAL**

Applicant : Szlufcik, et al.
App. No : 10/609,015
Filed : June 27, 2003
For : SEMICONDUCTOR ETCHING
PASTE AND THE USE THEREOF
FOR LOCALIZED ETCHING OF
SEMICONDUCTOR SUBSTRATES
Examiner : Vinh, L.
Art Unit : 1765

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

July 1, 2005

(Date)

Rose M. Thiessen, Reg. No. 40,202

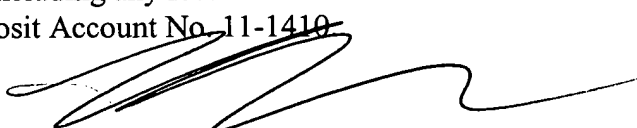
Mail Stop Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing in the above-identified application are the following enclosures:

- (X) Response to Restriction Requirement in 1 pages.
- (X) Return prepaid postcard.
- (X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410



Rose M. Thiessen
Registration No. 40,202
Attorney of Record
Customer No. 20,995
(619) 235-8550



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Szlufcik, et al.
Appl. No. : 10/609,015
Filed : June 27, 2003
For : SEMICONDUCTOR ETCHING
PASTE AND THE USE THEREOF
FOR LOCALIZED ETCHING OF
SEMICONDUCTOR
SUBSTRATES
Examiner : Vinh, L.
Group Art Unit : 1765

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

July 1, 2005

(Date)

Rose M. Thiessen, Reg. No. 40,202

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In a Restriction Requirement, mailed June 21, 2005, restriction was made to one of the following inventions: Claims 1-15, drawn to a method for etching a semiconductor substrate (Group I); Claims 16-23, drawn to a solar cell / semiconductor substrate / product (Group II); and Claims 24-25, drawn to an etching paste / composition / product (Group III).

Applicants hereby elect the invention of Group I (Claims 1-15), without traverse.

If the Examiner has any questions, he is invited to contact the undersigned directly.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: 7/1/05

By: 

Rose M. Thiessen
Registration No. 40,202
Attorney of Record
Customer No. 20,995
(619) 235-8550